BGA Heat Sink (High Aspect Ratio Ext.) Standard Pin Fin





Description: 21.00 x 21.00 x 11.40 mm BGA Heat Sink (High Aspect Ratio Ext.) Standard Pin Fin



Heat Sink Type: Standard Pin Fin

Heat Sink Attachment: N/A
Equivalent Part Number: N/A

*Image above is for illustration purpose only.

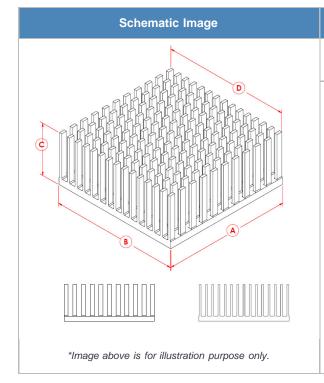
Features & Benefits

- Excellent balance of low cost and high performance in an aluminum heat sink.
- Designed for semiconductor devices with omni-directional airflow requirements.
- 6x6 pin array
- Available with a variety of thermal adhesive tape options. Contact sales@qats.com for product configurations.

Thermal Performance

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	15 °C/W	N/A °C/W	N/A °C/W	N/A °C/W	N/A °C/W	N/A °C/W	N/A °C/W
	Ducted Flow	0	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail



Dimension A	Dimension B	Dimension C	Dimension D	TIM	Finish	
21.00 mm	21.00 mm	11.40 mm	N/A mm	NO TIM	Black Anodized	

Notes:

- Dimension A and B refer to component size.
- Dimension C is the heat sink height from the bottom of the base to the top of the fin field.
- Thermal performance data are provided for reference only. Actual performance may vary by application
- ATS reserves the right to update or change its products without notice to improve the design or performance.
- ATS certifies that this heat sink assembly is RoHS-6 and REACH compliant.
- Contact ATS to learn about custom options available.

For more information, to find a distributor or to place an order, please contact us at 781-769-2800 (North America), sales@qats.com or www.qats.com.

